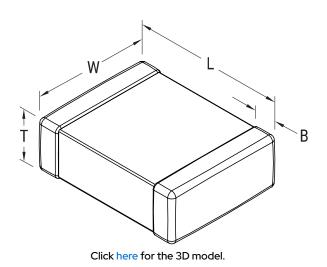




CBR-SMD RF COG, Ceramic, 3.3 pF, +/-0.25 pF, 500 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0805



General Information	
Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	12.03 mg
Notes	Solder Wave or Solder Reflow.
Shelf Life	78 Weeks
MSL	1

3.3 pF

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	0.85mm +/-0.1mm
В	0.5mm +/-0.2mm

2mm +/-0.2mm	Tolerance	+/-0.25 pF
1.25mm +/-0.2mm	Voltage DC	500 VDC
0.85mm +/-0.1mm	Dielectric Withstanding Voltage	750 VDC
0.5mm +/-0.2mm	Temperature Range	-55/+125°C
	Temp. Coefficient	COG
	Dissipation Factor	0.215%
	Dissipation ractor	0.21370
T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade Hour
T&R, 180mm, Plastic Tape 4000	·	
	0.85mm +/-0.1mm	1.25mm +/-0.2mm Voltage DC 0.85mm +/-0.1mm Dielectric Withstanding Voltage 0.5mm +/-0.2mm Temperature Range Temp. Coefficient

**Specifications** Capacitance

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